

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

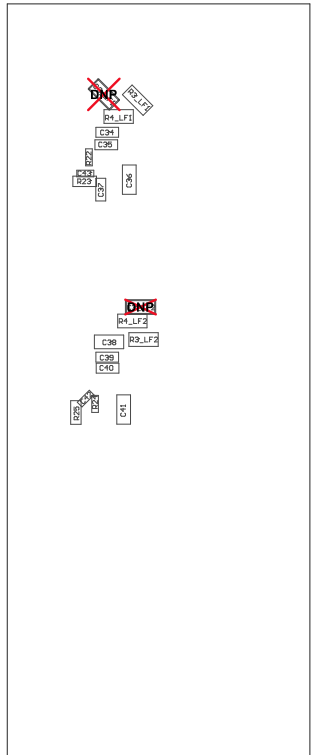
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #:	TIDA-01346	REV:	A	SUN REV:	Not In VersionControl
	TID #:	.TID				
PLOT NAME #	Top Assembly Drawing	GENERATED	1	4/6/2017	4:37:25 PM	TEXAS INSTRUMENTS

COMPONENTS MARKED "DNP" SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT:

001



PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01346	REV: A	SUN REV: Not In VersionControl
	TID #: -TID		
PLOT NAME = Bottom Assembly Drawing	GENERATED: 4/6/2017 4:30:25 PM	TEXAS INSTRUMENTS	

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